



Material Content Data Sheet



Sales Product Name		ISO1H815G		Issued		26. August 2018		
MA#		MA002952248						
Package		PG-DSO-36-21		Weight*		2096.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.123	0.05	0.05	535	535
chip_2	inorganic material	silicon	7440-21-3	1.164	0.06	0.06	555	555
chip_3	inorganic material	silicon	7440-21-3	16.733	0.80	0.80	7980	7980
leadframe	inorganic material	phosphorus	7723-14-0	0.388	0.02		185	
	non noble metal	zinc	7440-66-6	1.553	0.07		741	
	non noble metal	iron	7439-89-6	31.066	1.48		14815	
wire	non noble metal	copper	7440-50-8	1261.410	60.16	61.73	601563	617304
	noble metal	gold	7440-57-5	3.858	0.18	0.18	1840	1840
	encapsulation	organic material	carbon black	1333-86-4	1.523	0.07		726
encapsulation	plastics	epoxy resin	-	70.043	3.34		33403	
	inorganic material	silicondioxide	60676-86-0	689.773	32.90	36.31	328951	363080
leadfinish	non noble metal	tin	7440-31-5	15.044	0.72	0.72	7174	7174
plating	noble metal	silver	7440-22-4	0.644	0.03	0.03	307	307
solder	non noble metal	tin	7440-31-5	0.014	0.00		7	
	noble metal	silver	7440-22-4	0.020	0.00		10	
glue	non noble metal	lead	7439-92-1	1.330	0.06	0.06	634	651
	plastics	Polyimide	26023-21-2	1.204	0.06	0.06	574	574
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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